Minimum Component Size 0402 mm (01005 in.) Board Length Min. 50 mm (2 in.) / Max. 457 mm (18 in.) Board Width Min. 50 mm (2 in.) / Max. 457 mm (18 in.) Board Height Clearance (max) 35 mm (1.378 in.) Board Edge Clearance (min) 3.0 mm (0.125 in.) – bottom side only Component Types Inspected Standard SMT (chips, J-lead, gull-wing, BGA, etc.), through-hole, odd-form, clips, connectors, header pins, and others Component Types Inspected Missing, polarity, tombstone, billboard, flipped, wrong part, gross body and lead damage, and others Colder Joint Defects Categories Oslder bridge, opens, lifted leads, wettability, excess and in sufficient solder, debris, and others Colder Joint Defects Categories Oslder bridge, opens, lifted leads, wettability, excess and in sufficient solder, debris, and others Colder Joint Defects Categories Oslder bridge, opens, lifted leads, wettability, excess and in sufficient solder, debris, and others Cother Items Detected Gold-finger contamination, pin-in-hole, bent pins, debris, and many others Categories Component Measurement Component X, Y position and Rotation Categories Measuremet Gage R&R < 10% (down to 0402 mm components) Vision System Imagers 80 Megapixel Sensor 40 Megapixel Sensor Image Transfer Protocol PCle Lighting Strobe White Light (with dark/bright field) Resolution 12 μm pixel size 17 μm pixel size 17 μm pixel size 1 μmage Processing Statistical Appearance Modelling (SAM™) Technology Option: Autonomous Image Interpretation (Ai²) Technology Programming Simple inline or offline CAD Import Any column separated text file (Standard information required – ref. designator, XY, Angle, Part no.,) System Specifications Conveyor Height Adjustable to 840 – 990 mm (33.1 – 38.9 in.) Machine Interface SMEMA, RS232 and Ethernet Power Requirements 100 × 88.6 x 132.1 cm (W x D x H) Weight ~219 kgs (483 lbs.)	Inspection Capabilities	QX150i	QX100i
Board Length Min. 50 mm (2 in.)/ Max. 457 mm (18 in.) Board Width Min. 50 mm (2 in.)/ Max. 308 mm (12 in.) Component Height Clearance (min) 35 mm (1.378 in.) Board Edge Clearance (min) 3.0 mm (0.125 in.) – bottom side only Component Types Inspecte Standard SMT (chips, J-lead, gull-wing, BGA, etc.), through-hole, odd-form, clips, connectors, header pins, and others Component Defect Categories Missing, polarity, tombstone, billboard, flipped, wrong part, gross body and lead damage, and others Solder Joint Defects Categories Solder bridge, opens, lifted leads, wettability, excess and in sufficient solder, debris, and others Other Items Detected Gold-finger contamination, pin-in-hole, bent pins, debris, and many others Component Measurement Component X, Y position and Rotation Categories Component Measurement Component X, Y position and Rotation Categories Vision System Ilmager Tansfer Protocol PCle Lighting Strobe White Light (with dark/bright field) Resolution 12 μm pixel size 17 μm pixel size	Typical Scanning Speed	150 cm <sup>2</sup> /sec (23.25 in. <sup>2</sup> /sec)	
Board Width Min. 50 mm (2 in.)/ Max. 308 mm (12 in.)  Component Height Clearance (max)  35 mm (1.378 in.)  Board Edge Clearance (min)  3.0 mm (0.125 in.) – bottom side only  Component Types Inspected  Standard SMT (chips, J-lead, gull-wing, BGA, etc.), through-hole, odd-form, clips, connectors, header pins, and others  Missing, polarity, tombstone, billboard, flipped, wrong part, gross body and lead damage, and others  Solder Joint Defects Categories  Solder bridge, opens, lifted leads, wettability, excess and in sufficient solder, debris, and others  Other Items Detected  Gold-finger contamination, pin-in-hole, bent pins, debris, and many others  Component Measurement  Categories  Measurement Gage R&R  < 10% (down to 0402 mm components)  Vision System  Imager S  80 Megapixel Sensor  40 Megapixel Sensor  Image Transfer Protocol  Lighting  Strobe White Light (with dark/bright field)  Resolution  12 μm pixel size  17 μm pixel size  Image Processing  Statistical Appearance Modelling (SAM™) Technology.  Option: Autonomous Image Interpretation (Al²) Technology  Programming  CAD Import  Any column separated text file (Standard information required – ref. designator, XY, Angle, Part no.,)  System Specifications  Conveyor Height  Adjustable to 840 – 990 mm (33.1 – 38.9 in.)  Machine Interface  Power Requirements  100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps  System Dimensions  Weight  ~219 kgs (483 lbs.)	Minimum Component Size	0402 mm (01005 in.)	
Component Height Clearance (max)  Board Edge Clearance (min)  Component Types Inspected  Standard SMT (chips, J-lead, gull-wing, BGA, etc.), through-hole, odd-form, clips, connectors, header pins, and others  Component Defect Categories  Missing, polarity, tombstone, billboard, flipped, wrong part, gross body and lead damage, and others  Solder Joint Defects Categories  Solder bridge, opens, lifted leads, wettability, excess and in sufficient solder, debris, and others  Other Items Detected  Gold-finger contamination, pin-in-hole, bent pins, debris, and many others  Component Measurement  Component X, Y position and Rotation  Categories  Weasurement Gage R&R  <10% (down to 0402 mm components)  Vision System  Image Transfer Protocol  Lighting  Strobe White Light (with dark/bright field)  Resolution  12 μm pixel size  17 μm pixel size  Image Processing  Statistical Appearance Modeling (SAM™) Technology.  Option: Autonomous Image Interpretation (AI³) Technology  Programming  Simple inline or offline  CAD Import  Any column separated text file (Standard information required – ref. designator, XY, Angle, Part no.,)  System Specifications  Conveyor Height  Adjustable to 840 – 990 mm (33.1 – 38.9 in.)  Machine Interface  Power Requirements  100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps  System Dimensions  100 x 88.6 x 13.2.1 cm (W x D x H)  Weight  -219 kgs (483 lbs.)	Board Length	Min. 50 mm (2 in.)/ Max. 457 mm (18 in.)	
Board Edge Clearance (min)  3.0 mm (0.125 in.) – bottom side only  Component Types Inspected  Standard SMT (chips, J-lead, gull-wing, BGA, etc.), through-hole, odd-form, clips, connectors, header pins, and others  Missing, polarity, tombstone, billboard, flipped, wrong part, gross body and lead damage, and others  Solder Joint Defects Categories  Solder bridge, opens, lifted leads, wettability, excess and in sufficient solder, debris, and others  Other Items Detected  Gold-finger contamination, pin-in-hole, bent pins, debris, and many others  Component Measurement  Categories  Measurement Gage R&R  < 10% (down to 0402 mm components)  Vision System  Imagers  80 Megapixel Sensor  40 Megapixel Sensor  Image Transfer Protocol  Lighting  Strobe White Light (with dark/bright field)  Resolution  12 μm pixel size  17 μm pixel size  Image Processing  Statistical Appearance Modeling (SAM™) Technology.  Option: Autonomous Image Interpretation (Al²) Technology.  Option: Autonomous Image Interpretation (Al²) Technology  Programming  Simple inline or offline  CAD Import  Any column separated text file (Standard information required – ref. designator, XY, Angle, Part no.,)  System Specifications  Conveyor Height  Adjustable to 840 – 990 mm (33.1 – 38.9 in.)  Machine Interface  Power Requirements  100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps  System Dimensions  Weight  -219 kgs (483 lbs.)	Board Width	Min. 50 mm (2 in.)/ Max. 308 mm (12 in.)	
Component Types Inspected       Standard SMT (chips, J-lead, gull-wing, BGA, etc.), through-hole, odd-form, clips, connectors, header pins, and others         Component Defect Categories       Missing, polarity, tombstone, billboard, flipped, wrong part, gross body and lead damage, and other Solder Joint Defects Categories         Other Items Detected       Gold-finger contamination, pin-in-hole, bent pins, debris, and many others         Component Measurement Categories       Component X, Y position and Rotation         Measurement Gage R&R       < 10% (down to 0402 mm components)	Component Height Clearance (max)	35 mm (1.378 in.)	
pins, and others  Component Defect Categories Missing, polarity, tombstone, billboard, flipped, wrong part, gross body and lead damage, and other Solder Joint Defects Categories Solder bridge, opens, lifted leads, wettability, excess and in sufficient solder, debris, and others Other Items Detected Gold-finger contamination, pin-in-hole, bent pins, debris, and many others  Component Measurement Component X, Y position and Rotation Categories  Measurement Gage R&R < 10% (down to 0402 mm components)  Vision System  Imager 8 80 Megapixel Sensor 40 Megapixel Sensor  Image Transfer Protocol PCle  Lighting Strobe White Light (with dark/bright field)  Resolution 12 μm pixel size 17 μm pixel size  Image Processing Statistical Appearance Modeling (SAM™) Technology. Option: Autonomous Image Interpretation (AI²) Technology  Programming Simple inline or offline  CAD Import Any column separated text file (Standard information required – ref. designator, XY, Angle, Part no.,)  System Specifications  Conveyor Height Adjustable to 840 − 990 mm (33.1 − 38.9 in.)  Machine Interface SMEMA, RS232 and Ethernet  Power Requirements 100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps  System Dimensions 100 x 88.6 x 132.1 cm (W x D x H)  Weight ~219 kgs (483 lbs.)	Board Edge Clearance (min)	3.0 mm (0.125 in.) – bottom side only	
Solder Joint Defects Categories Other Items Detected Gold-finger contamination, pin-in-hole, bent pins, debris, and many others Component Measurement Categories  Measurement Gage R&R < 10% (down to 0402 mm components)  Vision System  Imagers 80 Megapixel Sensor PCIe Lighting Strobe White Light (with dark/bright field)  Resolution 12 μm pixel size Image Processing Statistical Appearance Modeling (SAM™) Technology. Option: Autonomous Image Interpretation (Al²) Technology Option: Autonomous Image Interpretation required − ref. designator, XY, Angle, Part no.,)  System Specifications  Conveyor Height Adjustable to 840 − 990 mm (33.1 − 38.9 in.)  Machine Interface Power Requirements 100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps  System Dimensions 100 x 88.6 x 132.1 cm (W x D x H) Weight  ~219 kgs (483 lbs.)	Component Types Inspected		
Other Items Detected       Gold-finger contamination, pin-in-hole, bent pins, debris, and many others         Component Measurement Categories       Component X, Y position and Rotation         Measurement Gage R&R       < 10% (down to 0402 mm components)         Vision System       Vision System         Imagers       80 Megapixel Sensor       40 Megapixel Sensor         Image Transfer Protocol       PCIe         Lighting       Strobe White Light (with dark/bright field)       17 μm pixel size         Resolution       12 μm pixel size       17 μm pixel size         Image Processing       Statistical Appearance Modeling (SAM™) Technology. Option: Autonomous Image Interpretation (AI²) Technology         Programming       Simple inline or offline         CAD Import       Any column separated text file (Standard information required – ref. designator, XY, Angle, Part no.,)         System Specifications         Conveyor Height       Adjustable to 840 – 990 mm (33.1 – 38.9 in.)         Machine Interface       SMEMA, RS232 and Ethernet         Power Requirements       100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps         System Dimensions       100 x 88.6 x 132.1 cm (W x D x H)         Weight       ~219 kgs (483 lbs.)	Component Defect Categories	Missing, polarity, tombstone, billboard, flipped, wrong	part, gross body and lead damage, and other
Component Measurement Categories       Component X, Y position and Rotation         Measurement Gage R&R       < 10% (down to 0402 mm components)	Solder Joint Defects Categories	Solder bridge, opens, lifted leads, wettability, excess and in sufficient solder, debris, and others	
Categories         Measurement Gage R&R       < 10% (down to 0402 mm components)	Other Items Detected	Gold-finger contamination, pin-in-hole, bent pins, debris, and many others	
Vision System         Imagers       80 Megapixel Sensor       40 Megapixel Sensor         Image Transfer Protocol       PCIe         Lighting       Strobe White Light (with dark/bright field)         Resolution       12 μm pixel size       17 μm pixel size         Image Processing       Statistical Appearance Modeling (SAM™) Technology. Option: Autonomous Image Interpretation (Al²) Technology         Programming       Simple inline or offline         CAD Import       Any column separated text file (Standard information required – ref. designator, XY, Angle, Part no.,)         System Specifications       Conveyor Height         Machine Interface       SMEMA, RS232 and Ethernet         Power Requirements       100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps         System Dimensions       100 x 88.6 x 132.1 cm (W x D x H)         Weight       ~219 kgs (483 lbs.)	•	Component X, Y position and Rotation	
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Resolution12 μm pixel size17 μm pixel sizeImage ProcessingStatistical Appearance Modeling (SAM™) Technology. Option: Autonomous Image Interpretation (AI²) TechnologyProgrammingSimple inline or offlineCAD ImportAny column separated text file (Standard information required – ref. designator, XY, Angle, Part no.,)System SpecificationsSystem SpecificationsConveyor HeightAdjustable to 840 – 990 mm (33.1 – 38.9 in.)Machine InterfaceSMEMA, RS232 and EthernetPower Requirements100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 ampsSystem Dimensions100 x 88.6 x 132.1 cm (W x D x H)Weight~219 kgs (483 lbs.)	Image Transfer Protocol	PCle	
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Option: Autonomous Image Interpretation (Al²) Technology  Simple inline or offline  CAD Import Any column separated text file (Standard information required – ref. designator, XY, Angle, Part no.,)  System Specifications  Conveyor Height Adjustable to 840 – 990 mm (33.1 – 38.9 in.)  Machine Interface SMEMA, RS232 and Ethernet  Power Requirements 100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps  System Dimensions 100 x 88.6 x 132.1 cm (W x D x H)  Weight ~219 kgs (483 lbs.)	Resolution	12 μm pixel size	17 μm pixel size
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System Specifications           Conveyor Height         Adjustable to 840 – 990 mm (33.1 – 38.9 in.)           Machine Interface         SMEMA, RS232 and Ethernet           Power Requirements         100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps           System Dimensions         100 x 88.6 x 132.1 cm (W x D x H)           Weight         ~219 kgs (483 lbs.)	Programming	Simple inline or offline	
Conveyor Height         Adjustable to 840 – 990 mm (33.1 – 38.9 in.)           Machine Interface         SMEMA, RS232 and Ethernet           Power Requirements         100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps           System Dimensions         100 x 88.6 x 132.1 cm (W x D x H)           Weight         ~219 kgs (483 lbs.)	CAD Import	Any column separated text file (Standard information required – ref. designator, XY, Angle, Part no.,)	
Machine Interface         SMEMA, RS232 and Ethernet           Power Requirements         100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps           System Dimensions         100 x 88.6 x 132.1 cm (W x D x H)           Weight         ~219 kgs (483 lbs.)	System Specifications		
Power Requirements         100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps           System Dimensions         100 x 88.6 x 132.1 cm (W x D x H)           Weight         ~219 kgs (483 lbs.)	Conveyor Height	Adjustable to 840 – 990 mm (33.1 – 38.9 in.)	
System Dimensions         100 x 88.6 x 132.1 cm (W x D x H)           Weight         ~219 kgs (483 lbs.)	Machine Interface	SMEMA, RS232 and Ethernet	
<b>Weight</b> ~219 kgs (483 lbs.)	Power Requirements	100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps	
	System Dimensions	100 x 88.6 x 132.1 cm (W x D x H)	
Machine Installation <1 hour	Weight	~219 kgs (483 lbs.)	
	Machine Installation	<1 hour	

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# QX150i<sup>TM</sup> 2D AOI High Value, Flexible Inspection for All Applications SMT China Vision Award for QX150i Ideal for Selective Solder and **Pre-Reflow Applications**

## QX150i™ Intelligent Sensing Technology

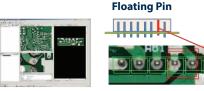
The SIM (Strobed Inspection Module) is the core engine behind every QX150i<sup>™</sup> system enabling 'on-the-fly' high performance inspection. Designed and manufactured exclusively by CyberOptics, the SIM is absolutely calibration-free and illuminates only when needed – reducing cost of ownership and power consumption.

An all-new SIM on the QX150i<sup>TM</sup> is designed with enhanced illumination - delivering the best 01005 and solder joint inspection performance ever. With an 80 Megapixel sensor and higher resolution (12 μm), you get crisp, perfect quality images for more accurate defect review.



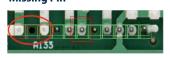
SIM (Strobe Inspection Module)

#### **Selective Soldering Inspection**









#### **Pre-Reflow Inspection**





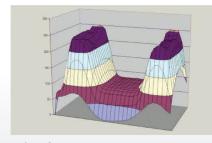




## Inspect 'Anything'

CyberOptics' Al<sup>2</sup> (Autonomous Image Interpretation) technology is designed for both low volume high mix, and high volume low mix Applications, and builds on the proven success of our Statistical Appearance Modeling technology. Al<sup>2</sup> is all about keeping it simple - no parameters to adjust or algorithms to tune. And, you don't need to anticipate defects or pre-define variance either – Al<sup>2</sup> does it all for you.

Just draw a box, show a few good examples and you are ready to inspect just about anything. Simply add good examples to the Ai<sup>2</sup> model and the false call rates reduce significantly providing a very robust inspection solution.



Al<sup>2</sup> Software: Unique Image Processing Technique



**Components Inspected/ Detected** 

## AOISOFTWARE

### **3-Easy-Steps Programming**

Our latest software improvements take programming to a whole, new level – zero to production ready in **less than 13 minutes!** All this is made possible, with an all-new data-rich, pre-loaded library and automated scripts that collect examples and update models – all on their own.



< 13 min programming\*

\*For pre-defined parts

**Simplified Programming Process** 

## Al<sup>2</sup> - Faster, Simpler, and Smarter

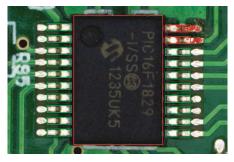
With Al<sup>2</sup> technology, programming gets even faster – with a 90% reduction in examples required to create a complete production ready programme – you will achieve superior defect detection and low false call rates even with just **one example**. This means significantly lower tuning time and quality results with one panel inspection. Perfect for those high-mix or low volume applications!

With its unique ability to 'ignore' bad examples in a model, Al<sup>2</sup> offers precise discrimination even with excessive variance and minimizes effects of outlier examples. Plus, it is a lot simpler with full support for unsupervised and semi-automatic model training. And, examples are pre-sorted so you can select and clear the ones you don't need – very quickly. The pixel marking feature highlights defective spots, so you can identify genuine defects instantly.

## Worst Probability

Best Probability

**Intelligent Ranking of Examples** 



**Active Pixel Marking** 

## **Fast, Scalable SPC Solution**

CyberReport<sup>™</sup> offers full-fledged machine-level to factory-level SPC capability with powerful historical analysis and reporting tools delivering complete traceability for process verification and yield improvement. CyberReport<sup>™</sup> is easy to setup and simple to use while providing fast charting with a compact database size.



